

FIG. 1

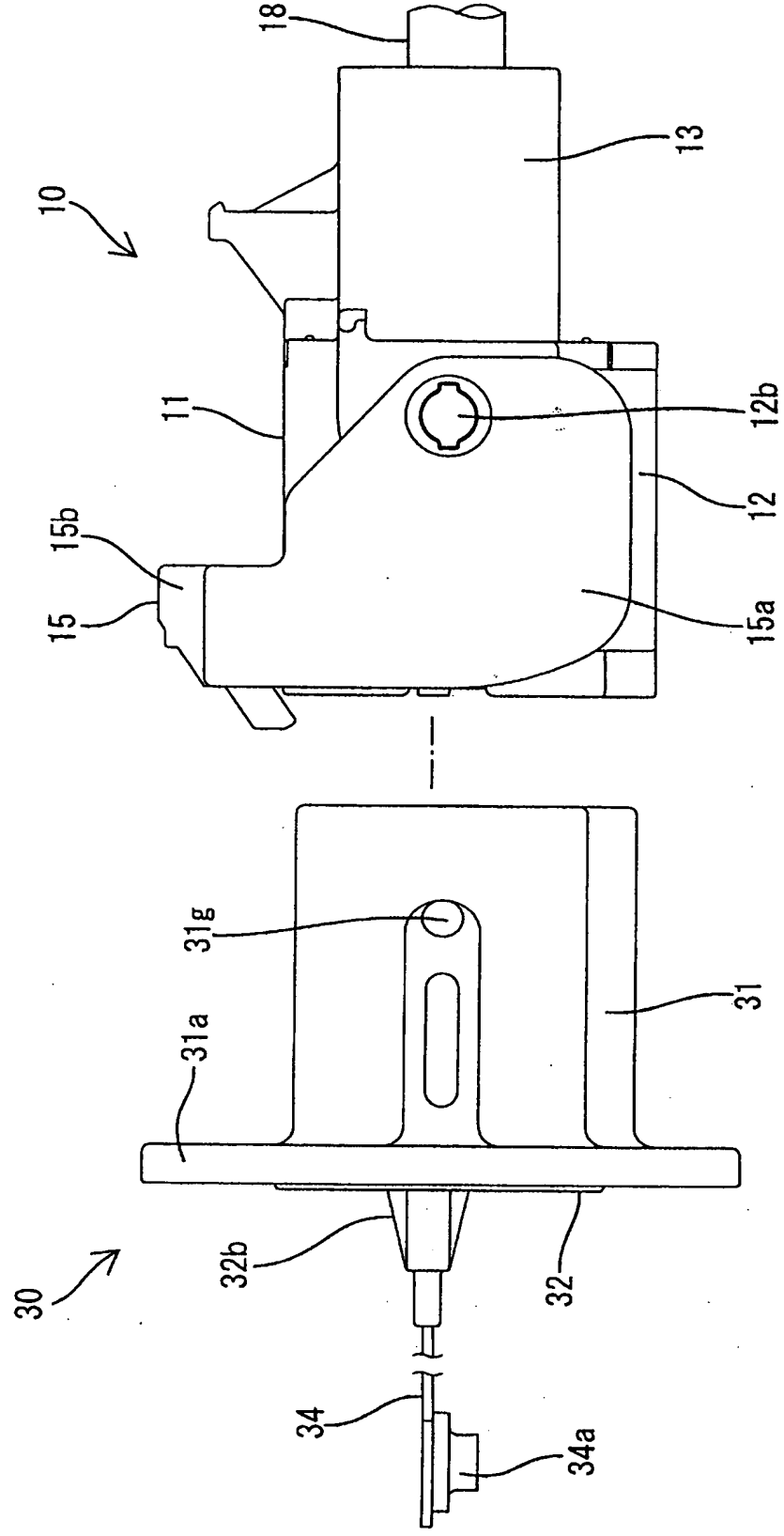


FIG. 2

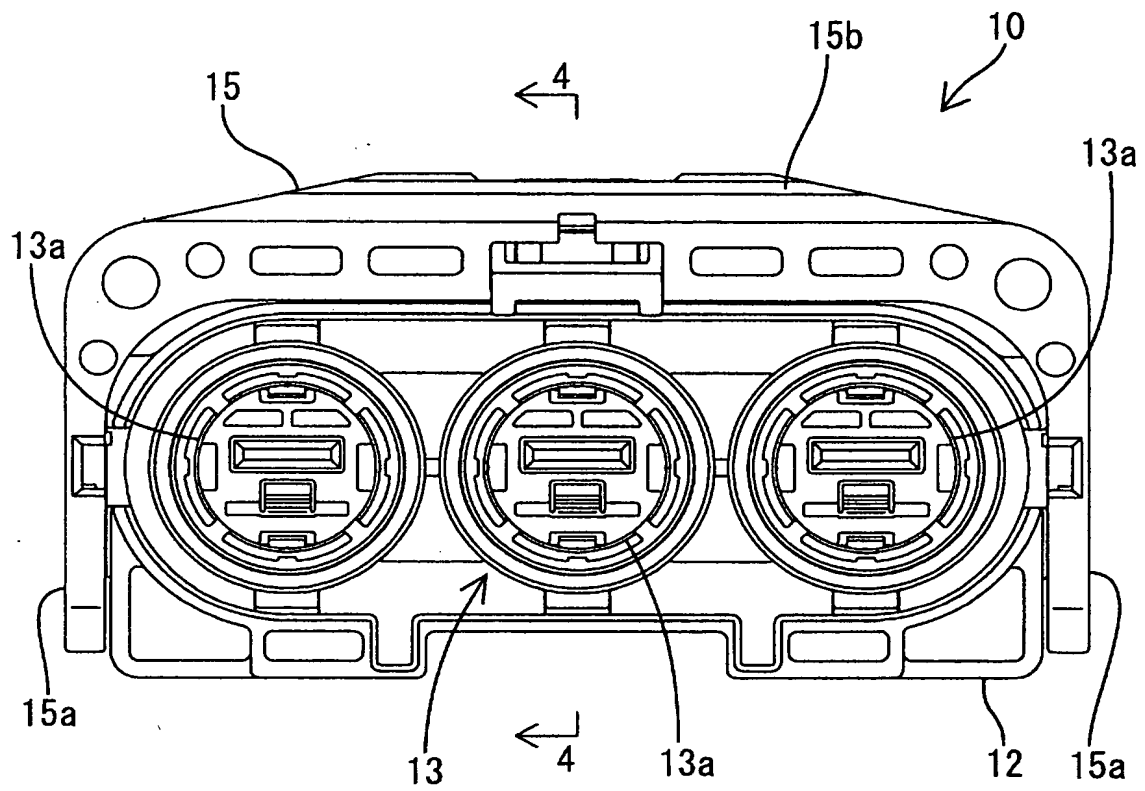
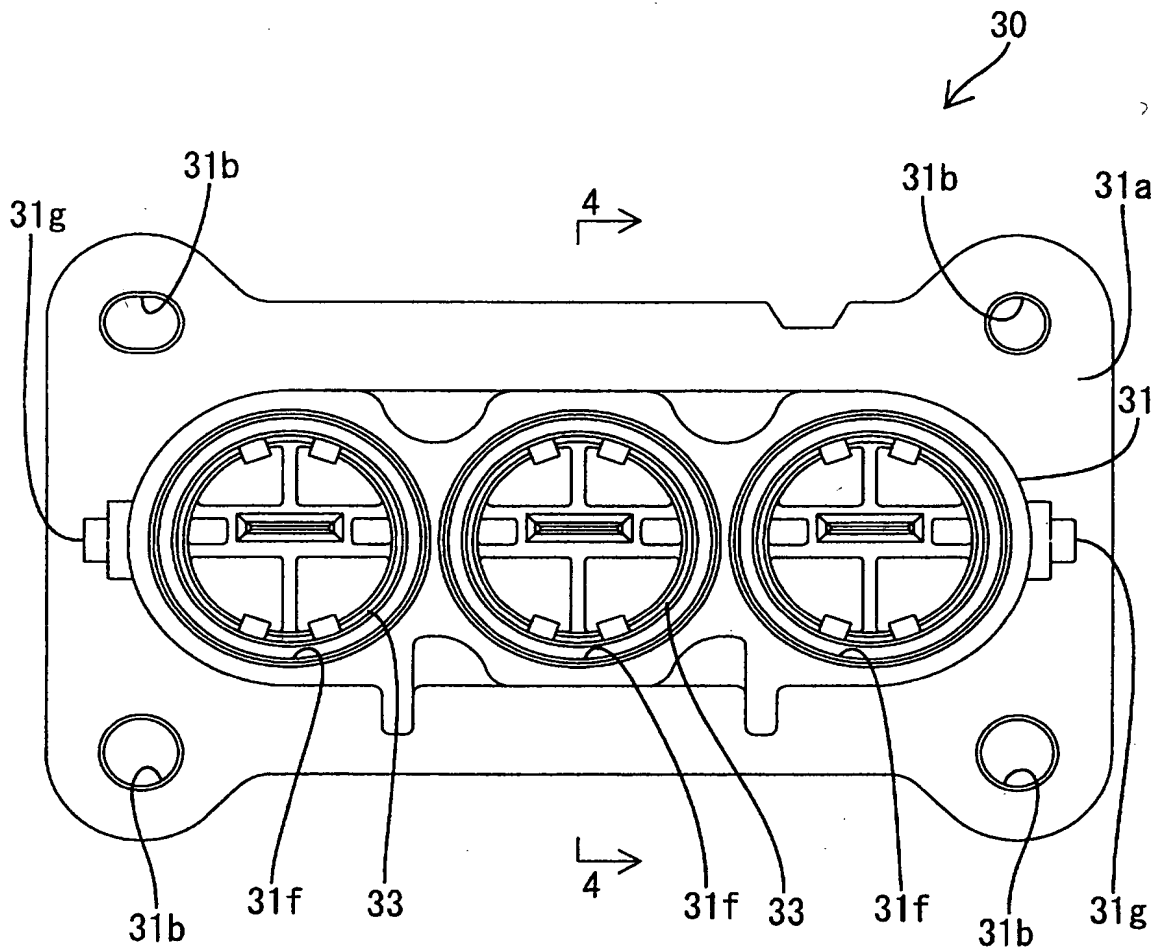


FIG. 3



This figure shows a cross-sectional view of a complex electronic assembly, labeled 10. The assembly consists of multiple layers and components. At the top, there is a layer 11 with features 12 and 13. Below this is a layer 14 containing a central component 15, which appears to be a chip or sensor, mounted on a base 16. A series of vertical vias or pins 17 connect different layers. Layer 18 contains a patterned region 19. Below layer 18 is another layer 20 with features 21 and 22. A bottom-most layer 23 is shown. Various other components are labeled with numbers like 13a, 13b, 13c, 13d, 13e, 13f, 14a, 14b, 15, 16, 17, 18, 19, 20, 21, 22, 23, 24, 25, 26, 27, 28, 29, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 40, 41, 42, 43, 44, 45, 46, 47, 48, 49, 50, 51, 52, 53, 54, 55, 56, 57, 58, 59, 60, 61, 62, 63, 64, 65, 66, 67, 68, 69, 70, 71, 72, 73, 74, 75, 76, 77, 78, 79, 80, 81, 82, 83, 84, 85, 86, 87, 88, 89, 90, 91, 92, 93, 94, 95, 96, 97, 98, 99, 100.

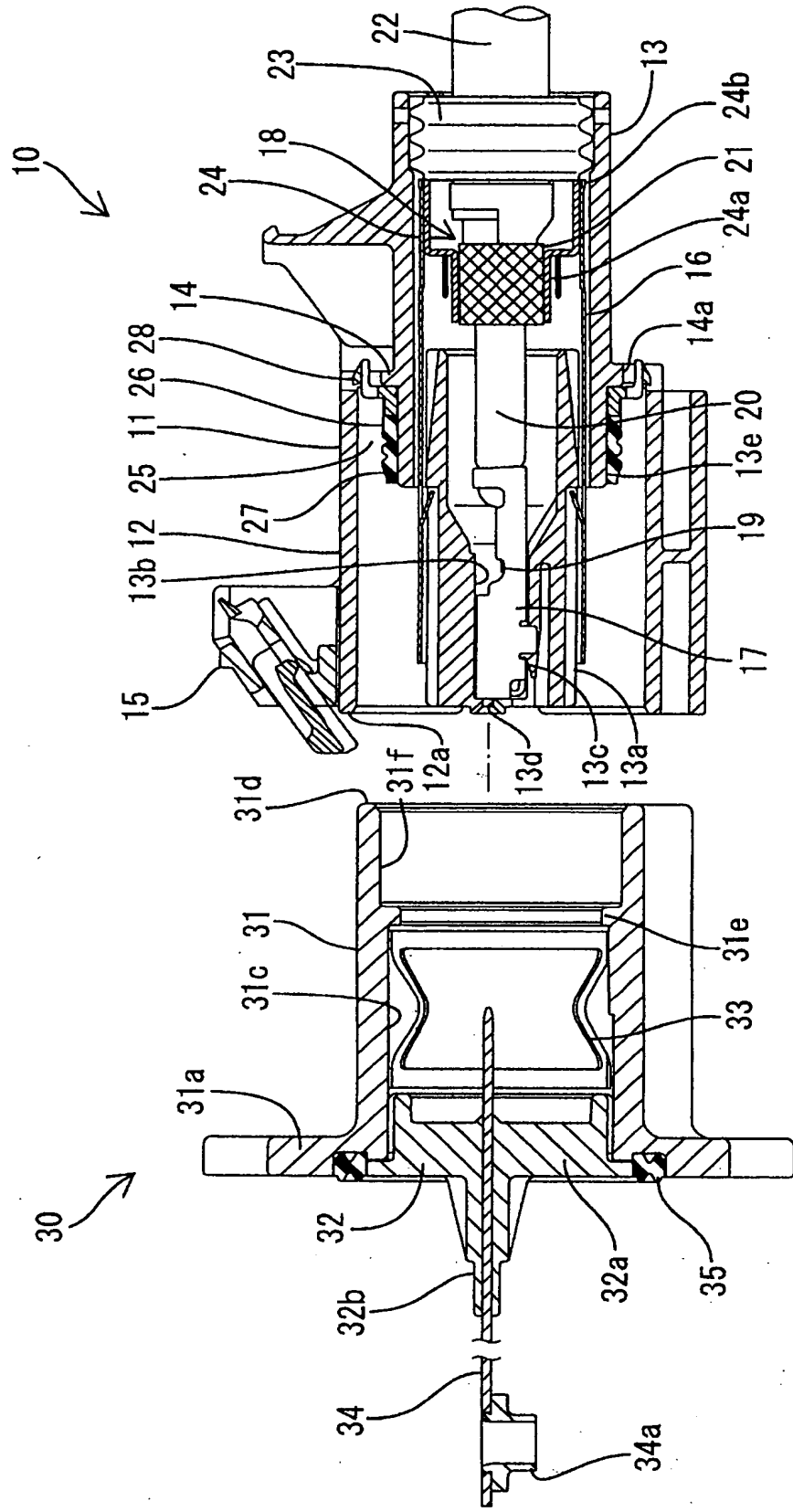


FIG. 5

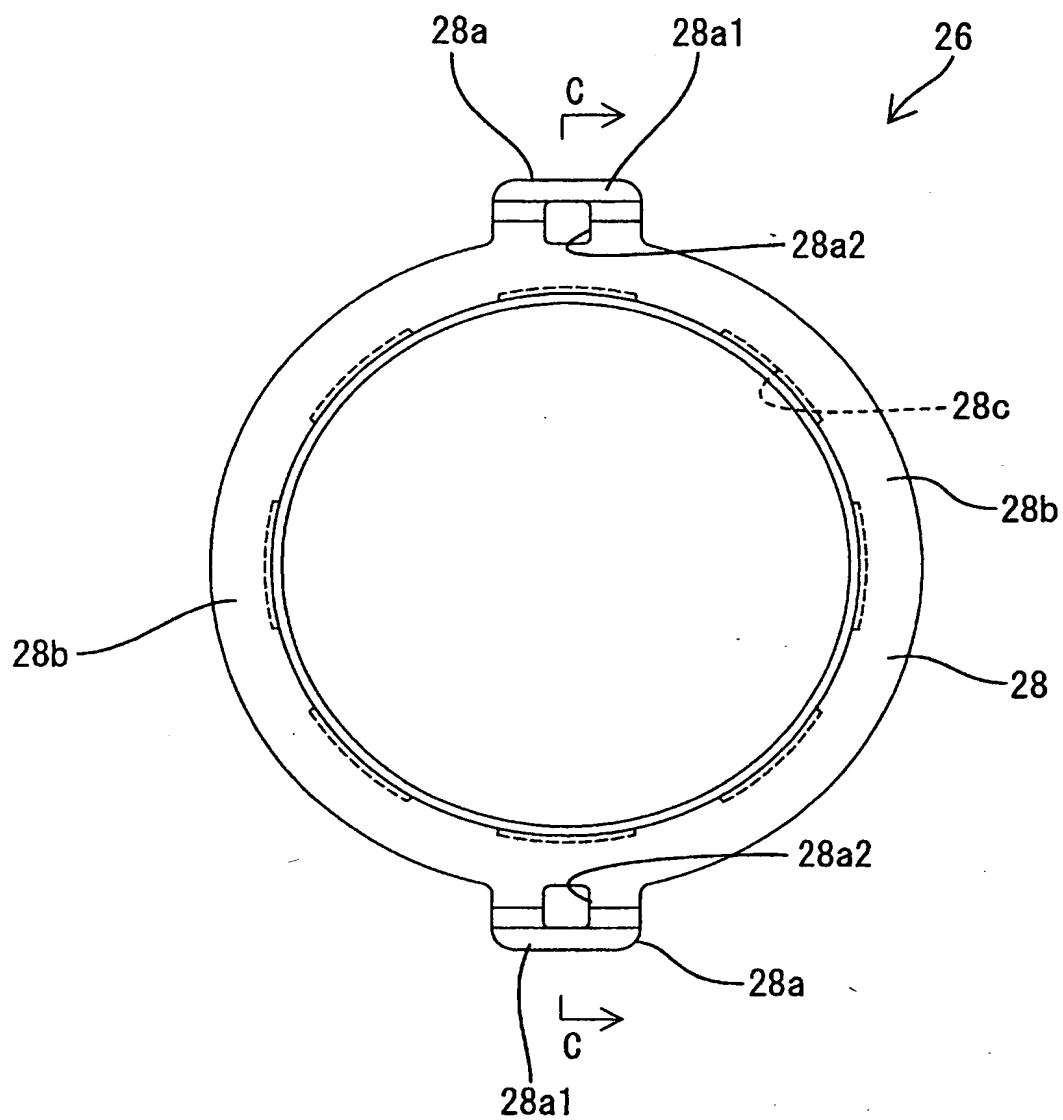


FIG. 6

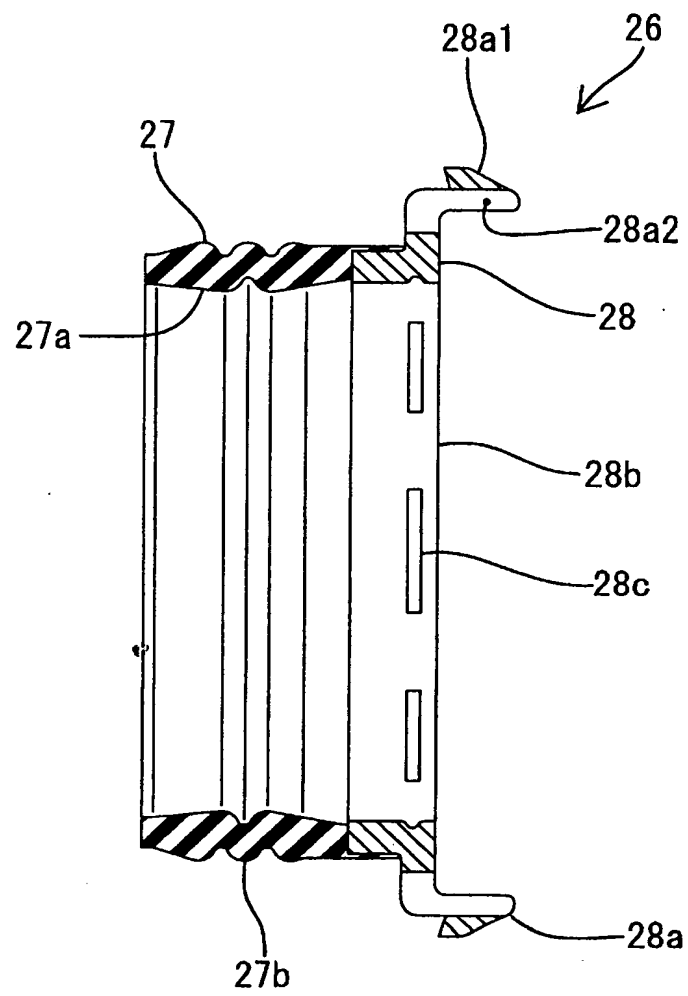


FIG. 7

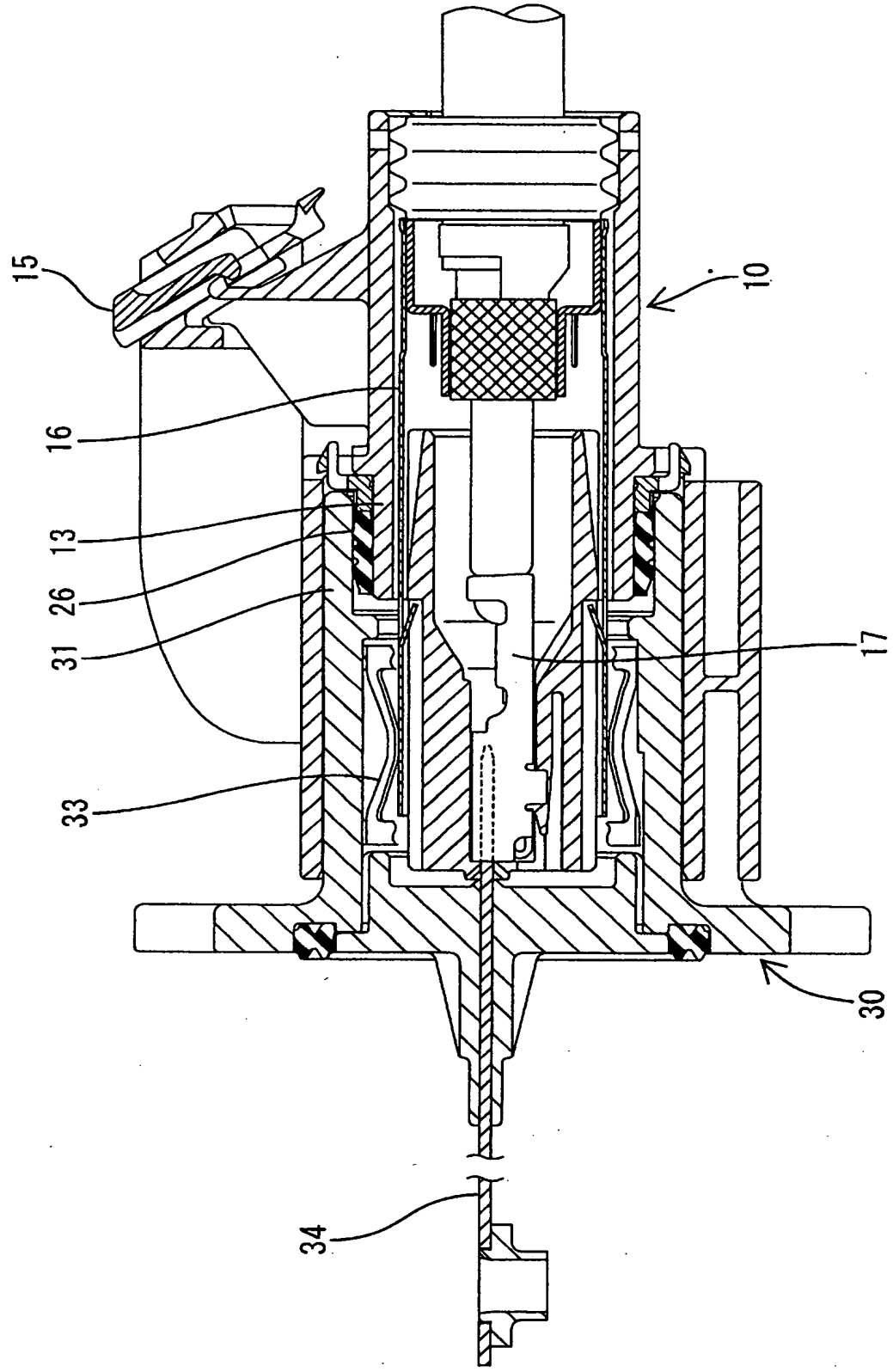


FIG. 8

